

Anode charge-up in resistive Micromegas and its quenching effect on spark development

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Intro

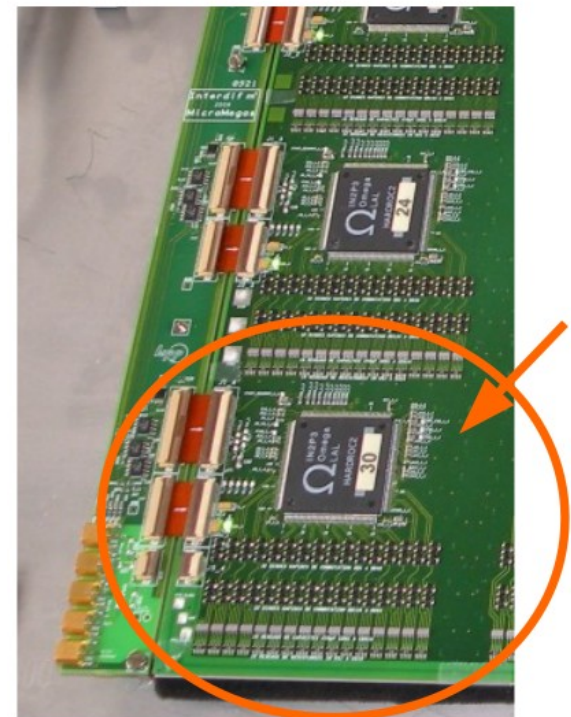
This is a side-study of our main project : Micromegas calorimetry

More specifically Micromegas for a LC-SDHCAL or a HL-LHC forward detector

Calorimetry = large energy deposits = we need spark protections

Diodes on PCB are not elegant for a 10^6 channel system

+ spark dead-time prohibitive for high-rate applications



Intro

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Diodes on PCB are not elegant for a 10^6 channel system

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Supress sparks with R-electrodes

Several on the market !

R-Layer on the readout electrodes (à la RPC, GridPix)

R-layer + Insulator (à la Dixit)

R-layer + metallic grid (à la Rwell THGEM)

R-layer + Insulator + through-PCB via

Embedded-R

R-layer			
RO-pads			

Last one turned out to be surprisingly interesting...

R-layer			
Insulator			
RO-pads			

Embedded resistors

Charge evacuation is vertical

No spread of signal to neighboring pads to fully exploit RO granularity
LC-calorimetry = imaging calorimetry = SDHCAL with 1x1 cm² cells

Resistance can be tuned (shape of embedded-R)

Nice to optimise for high-rate capability !
Which brings the question :

How low can we go with the resistance ?

Too high : RPC-like rate capability and no spark
Too low : MPGD-like rate capability with sparks

PS : we have segmented pads, so we don't mind low-R

Charge can not be shared with neighbors

First : try to predict what happens... not sure !
Quickly after : make prototypes of $\neq R$

R-pad		
Insulator	Via	
R-embedded		
	Via	Insulator
RO-pad		

4

Spark quenching

Spark development

Is a diverging process involving an initiating avalanche + its successors

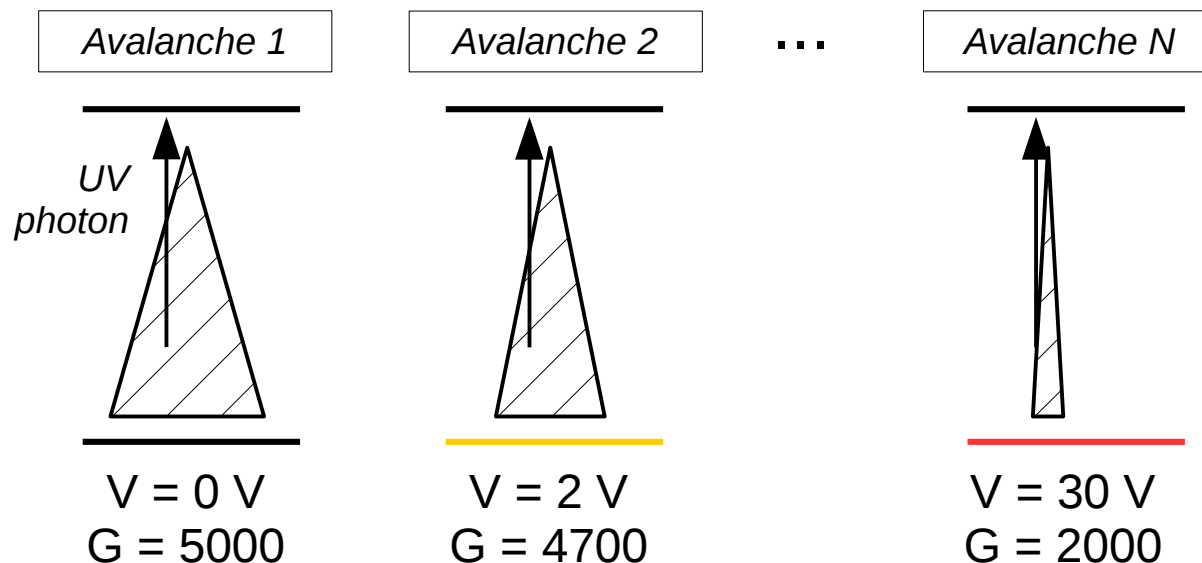
Initiating avalanche : traversing particles (or mechanical imperfections, edges...)

Successors : photon-feedback, photo-ionisation of impurities in the gas

Our (current) understanding

R-surface charges-up which reduces the field and stops the photon feedback

After some time, the excess charge is evacuated and the field is restored

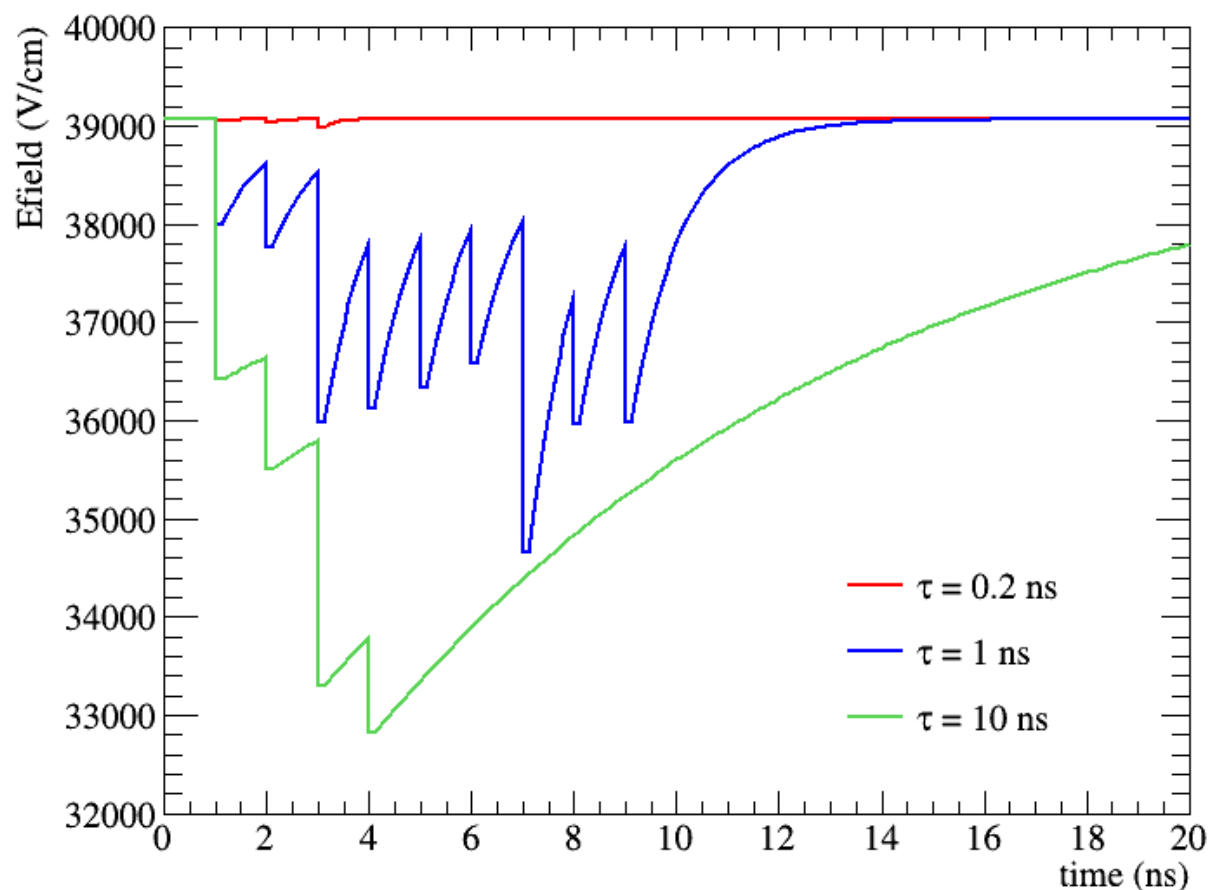


Spark quenching & timing

Relaxation time (τ) should not be too short !

Otherwise successors will feel the full field (= metallic anode)

Toy Monte Carlo of Efield versus time : large field drop when $\tau > \Delta t$ (= 1 ns here)



Δt = time interval between successors = e-drift time in ampli. gap (~ 1 ns)

Feedback : ~ 3 photoe- from initiating avalanche (Poisson)

Successors are multiplied by a factor that depend on the anode voltage

Anode voltage :
(+) charge from gas gain
(-) charge drained out

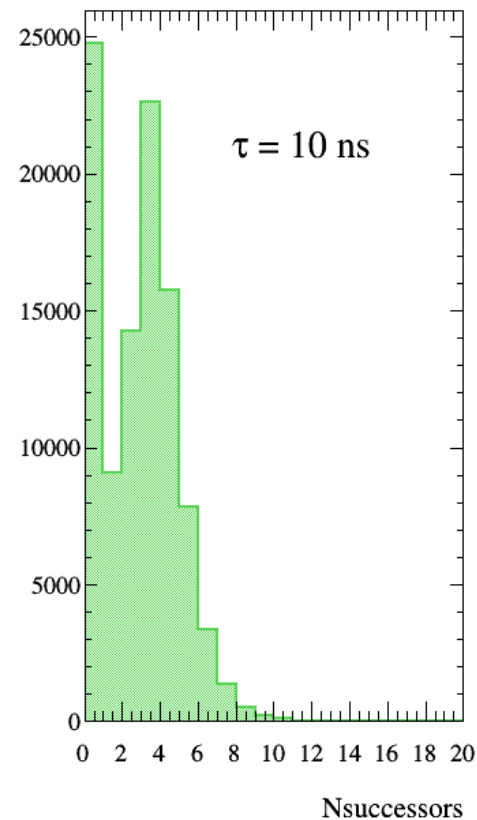
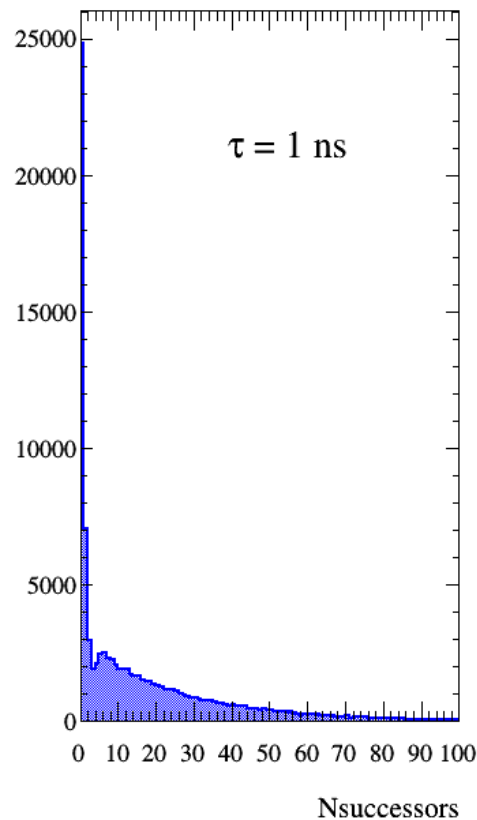
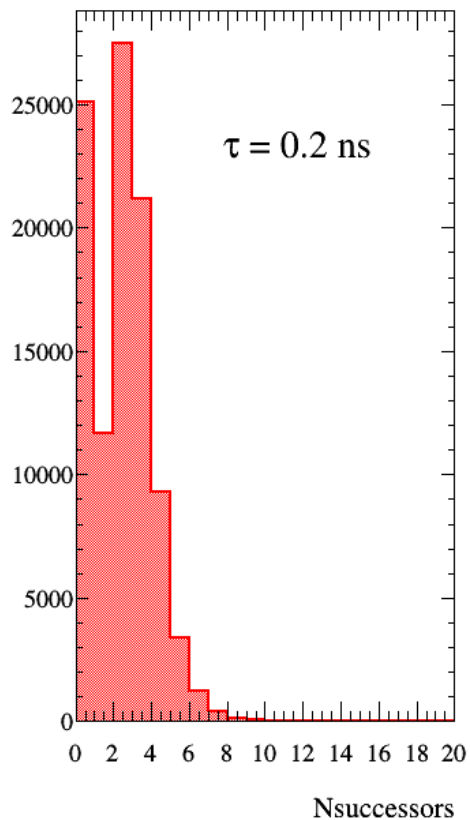
Spark quenching & timing

$\tau \ll \Delta t$ Field readily restored, quickly goes to spark, few successors

$\tau \sim \Delta t$ Field oscillations, instable regime, several successors

$\tau \gg \Delta t$ Field strongly reduced, spark is avoided, few successors

The critical value of τ is given by the timescale of the avalanche development.



$\Delta t = 1 \text{ ns}$

*128 μm gap
40 kV/cm
Ar/CO₂ 90/10*

Testing the model

Build prototypes of different τ by changing the value of R

Use paste of different resistivity ($100 \text{ k}\Omega/\square$ & $1 \text{ k}\Omega/\square$)

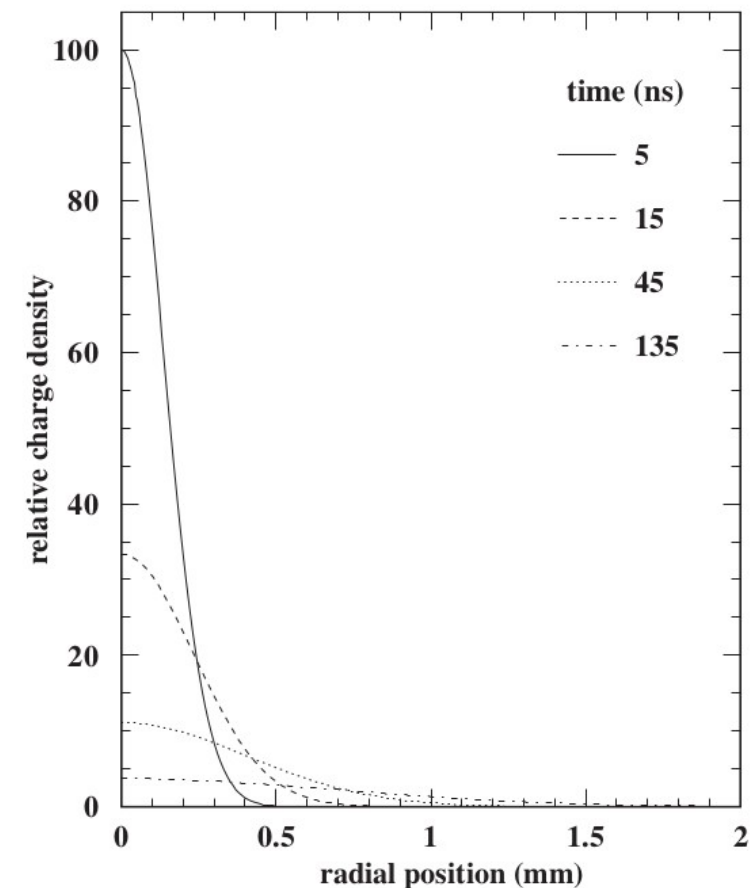
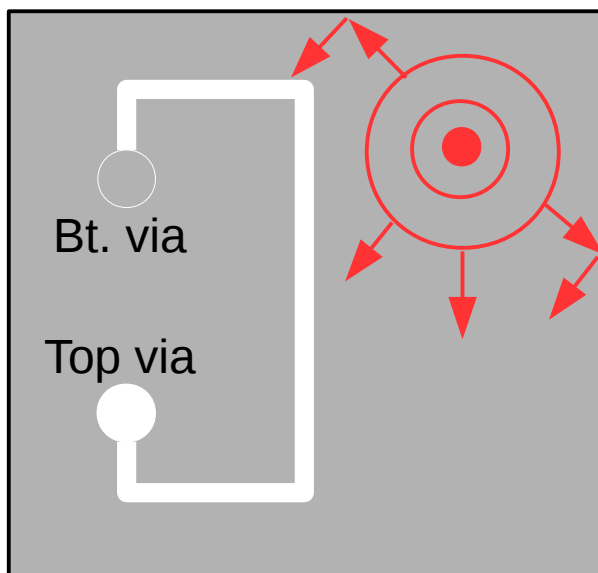
Use embedded resistors of different pattern (shape & number of via)

Not exactly sure how this will affect the value of τ

= RC only in case of an ideal geometry :

infinite R-layer (grounded on sides) on insulator

Complicated charge motion (only way out is the via)



The prototypes

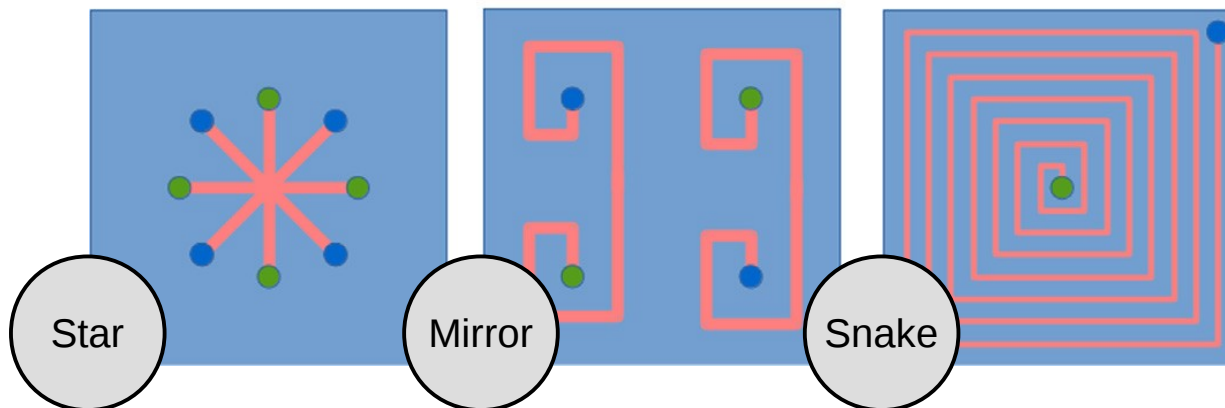
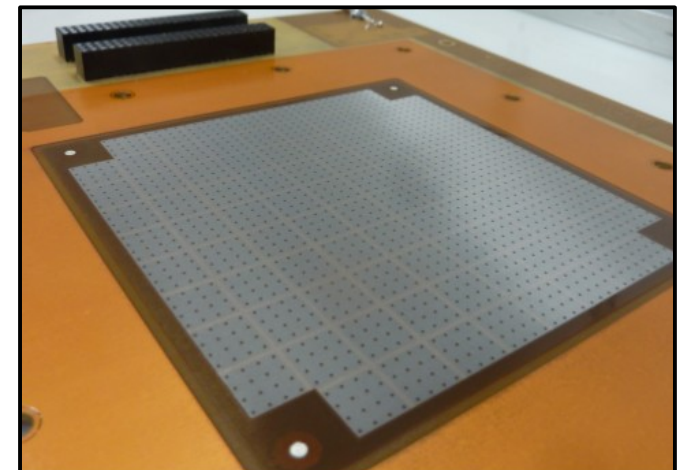
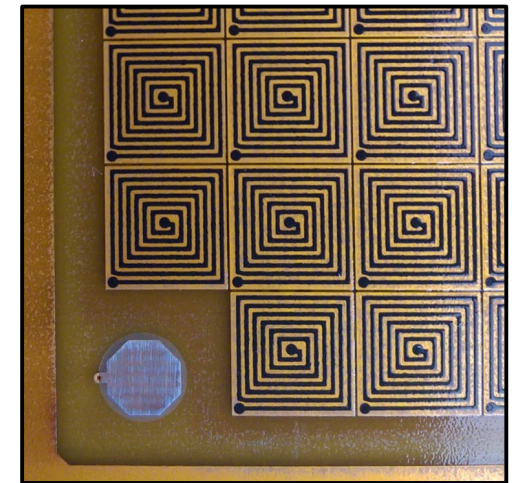
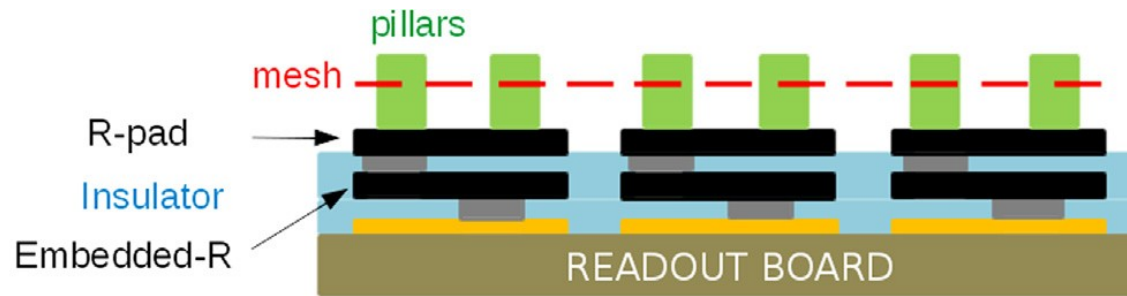
Pad boards

10X10 matrix of 1x1 cm² pads

Routing on the outside to a 'Gassiplex' connector (96 channels)

R-structures and Bulk-Micromegas

Serigraphy and photolithography at CERN MPGD workshop



Interlude 1 : energy resolution

We are not breaking records !

Top coverlay pressed on the embedded-R

Pattern probably transferred to the R-pad surface = poor ampli. gap uniformity

Can be improved by polishing

Digital calorimetry = counting hits...

Resolution does not matter

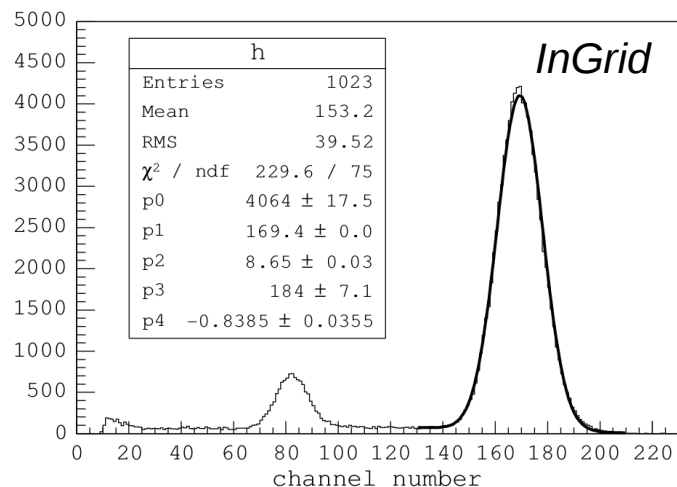
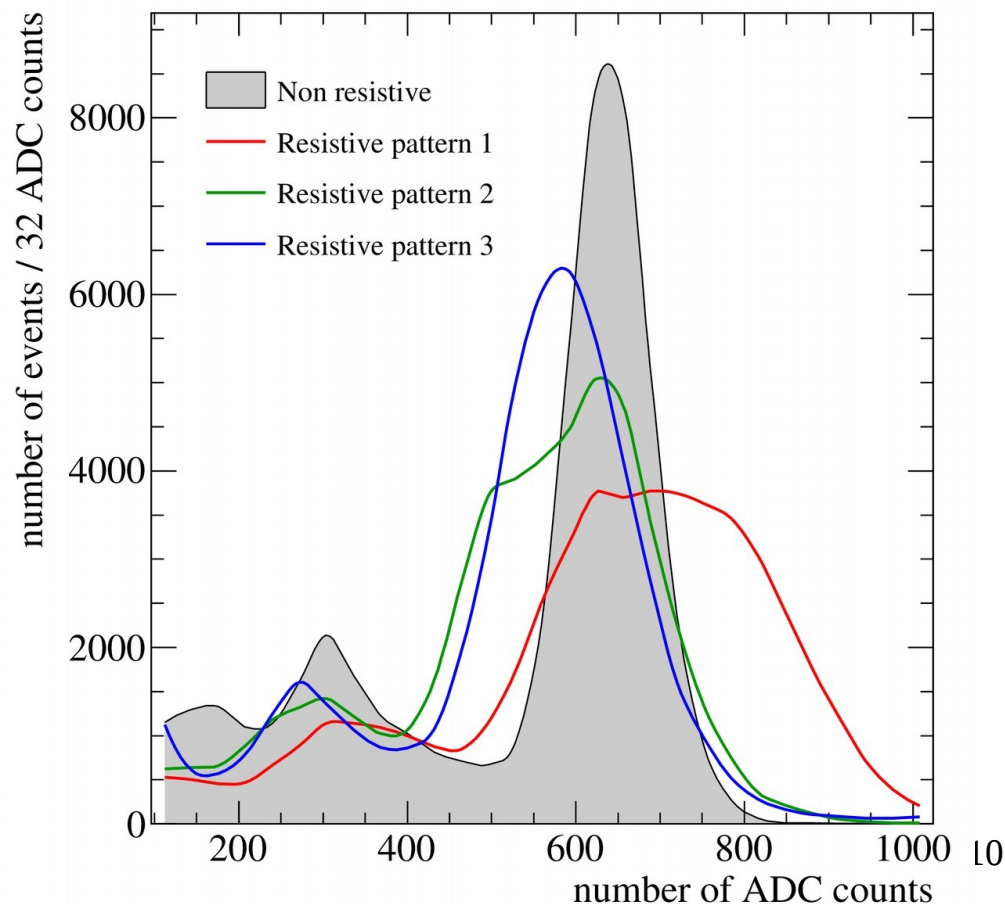


Figure 6.14: ^{55}Fe spectrum recorded in a P10 mixture. The K_β line was strongly absorbed by a $10\ \mu\text{m}$ thin Cr foil. The parameters of a gaussian (p_0 - p_2) and a linear (p_3 , p_4) function were adjusted to the photo-peak.



Interlude 2 : signal proportionality

Mesh to R-pad capacitance $\sim 70 \text{ nF/m}^2$: loss of proportionality for point-like events ?

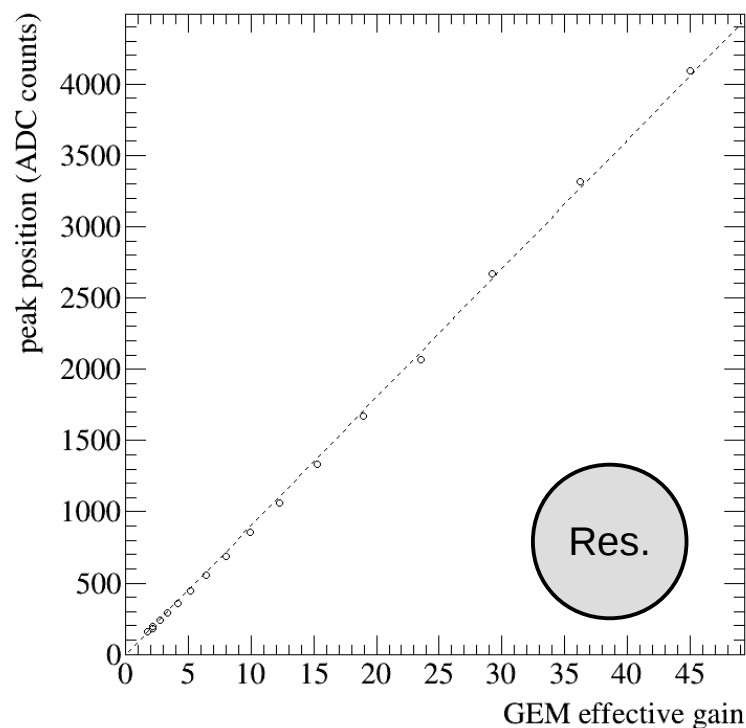
e.g. when several primary electrons arrive in the same mesh hole

Last arriving electrons might feel a reduced field = non-linear response

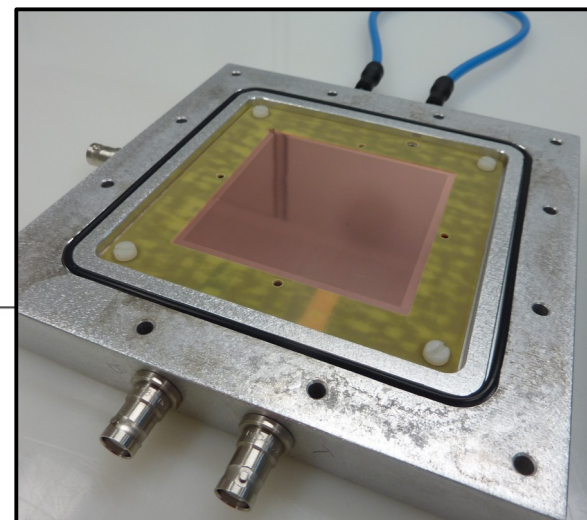
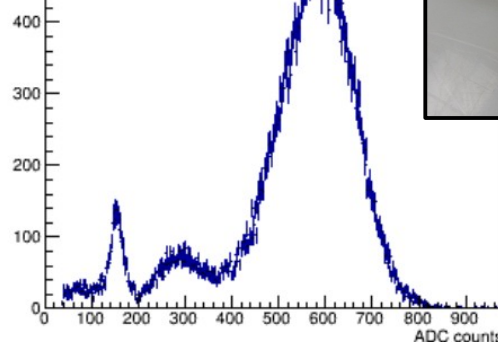
Drift distance above/below GEM injector $\sim 10/3 \text{ mm}$ (Ar/CO₂ 90/10)

230 primaries in ~ 5 GEM holes, each secondary in ~ 5 mesh holes

Response is linear up to testable GEM gains



Std.



Measuring the relaxation time

Let's use an Xgun !

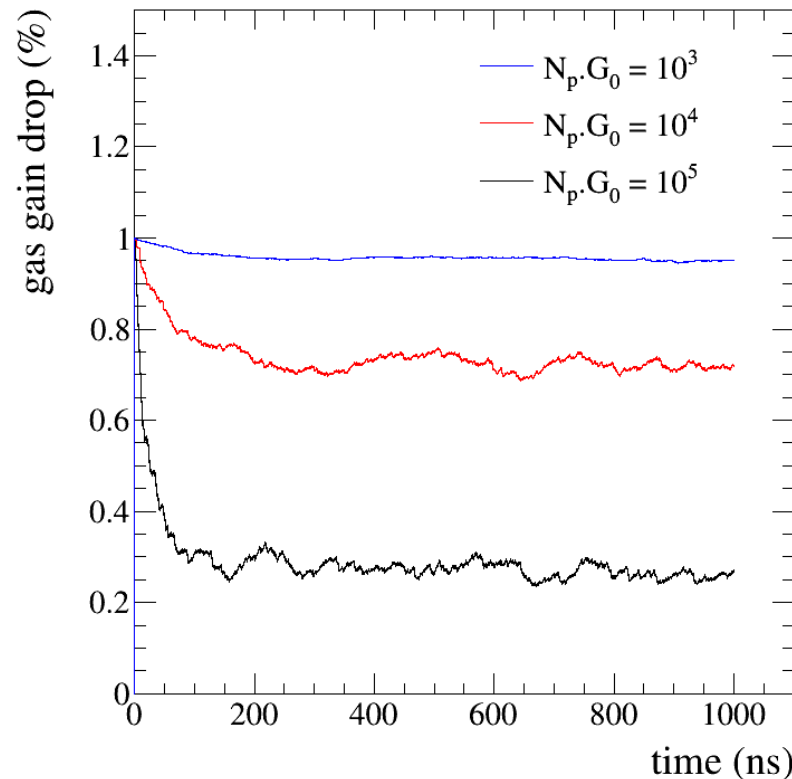
The detector current will saturate at high rate, this should tell us about τ ...

Mesh current : $I \sim I_0 / (1 + B R I_0)$

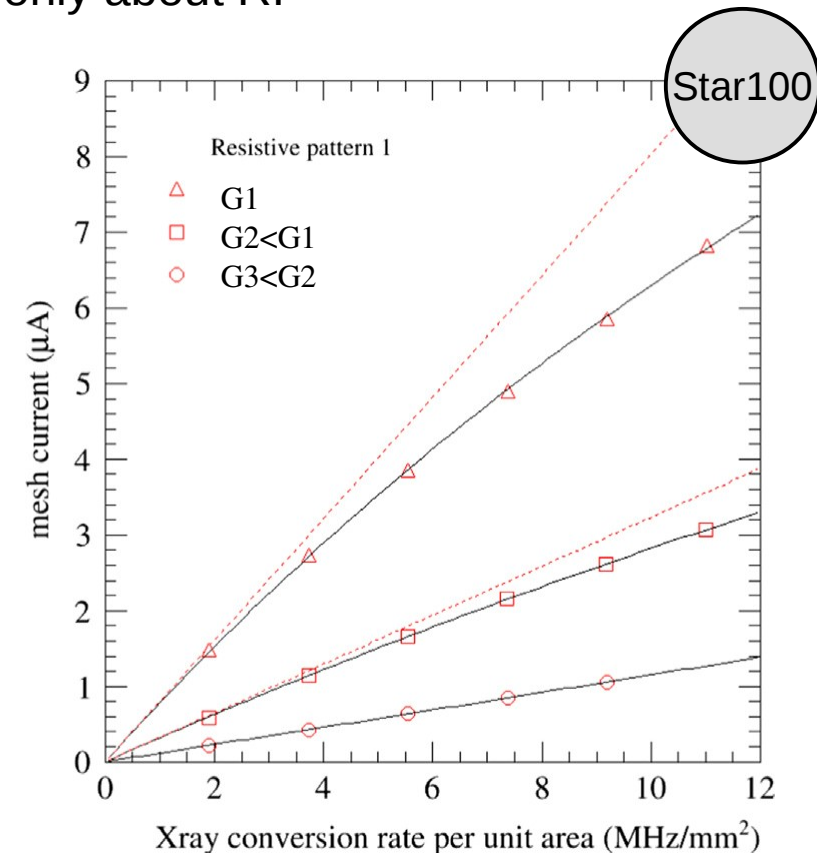
$$I = \Phi N_p G = \Phi N_p G_0 \exp(-B \Delta V) = I_0 \exp(-B R I) \sim I_0 (1 - B R I)$$

The asymptotic current does not tell us about τ , only about R .

(left)
Toy MC
 $\Phi = 1 \text{ GHz}$
 $\tau = 100 \text{ ns}$



(right)
Xgun data
 $\Phi < 80 \text{ MHz}$
 $\tau = ?$



Measuring the resistance

Mesh current : $I \sim I_0 / (1 + B R I_0)$

The asymptotic current does not tell us about τ , only about R .

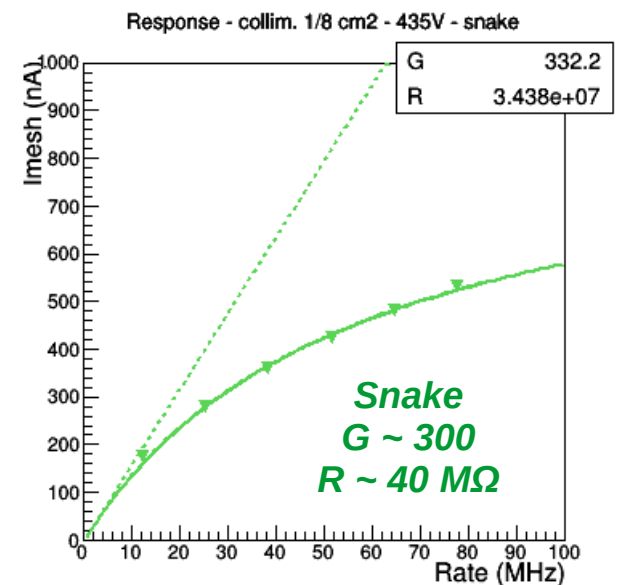
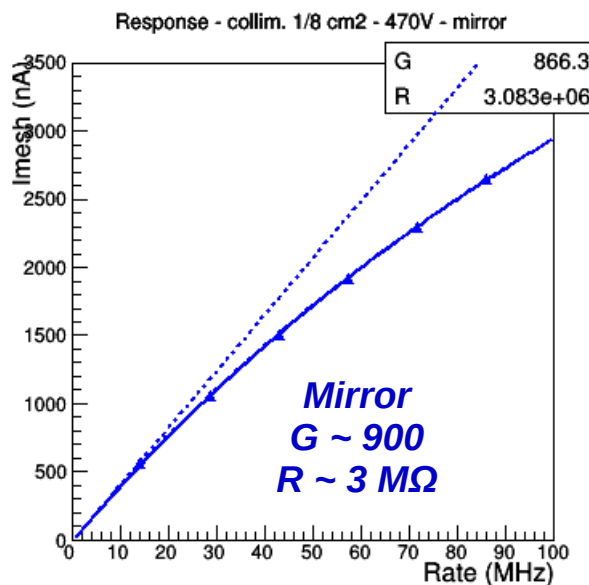
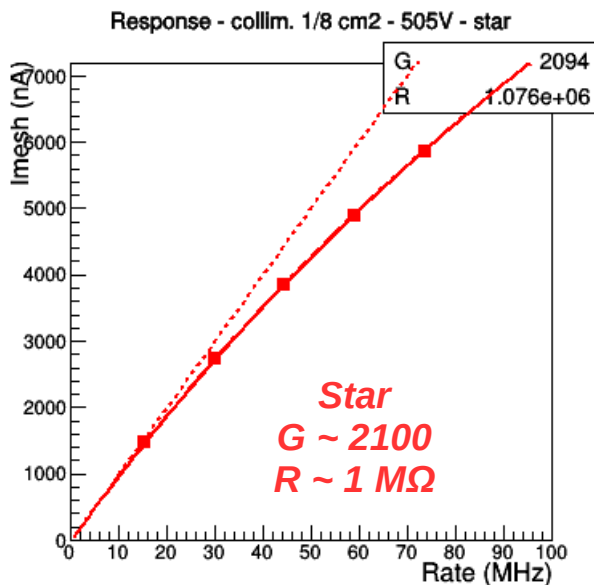
Replacing I_c by $(\Phi N_p G_c)$, one can fit the gain and R to the data

Nota Bene : the X-ray beam (8 keV) collimation is 8 mm²

The prototypes withstand rates up to 10 MHz/mm² with no sparks

The one with $R = 1 \text{ M}\Omega$ shows little deviations from linearity up to 1 MHz/mm²

= **Efficiency plateau up to 1 MHz/mm²**



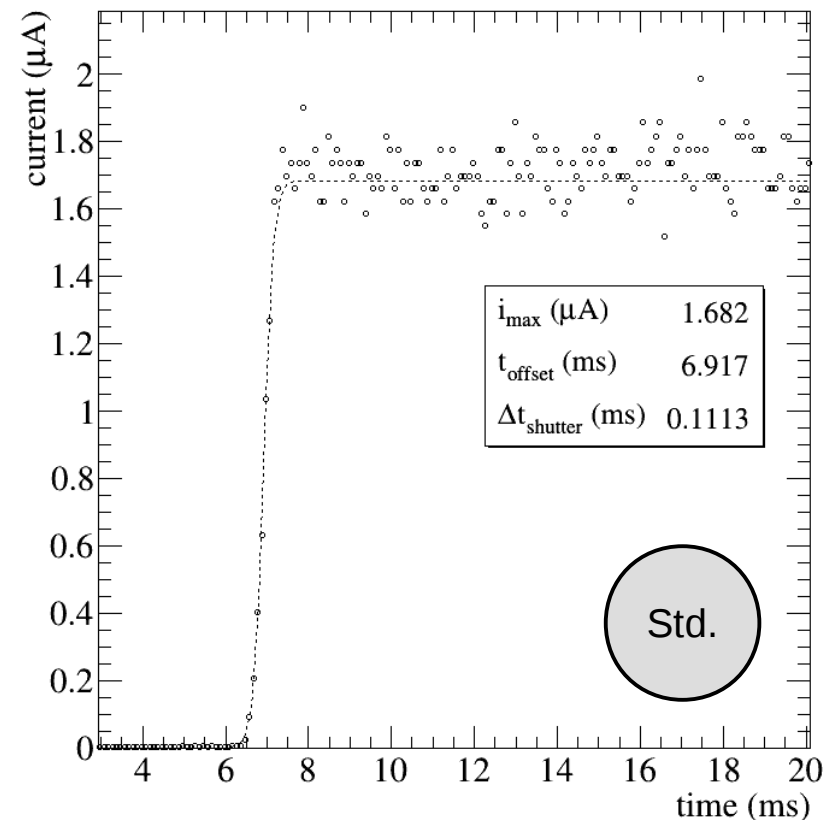
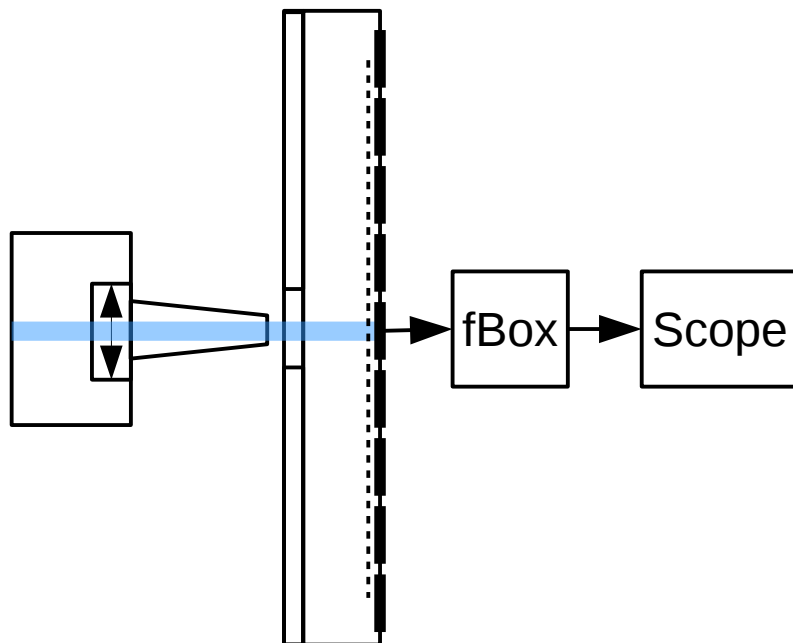
Measuring the relaxation time, once again

We see only the steady regime and miss the initial current peak

Try a faster readout : reading power supply \rightarrow recording pad-current on scope
Sensitive current-meter ('FemtoBox') available in RD51 lab. at CERN

With a non-resistive prototype, we measure a shutter time of $\sim 110 \mu\text{s}$

This means, the measurement is sensitive to relaxation time larger than $100 \mu\text{s}$



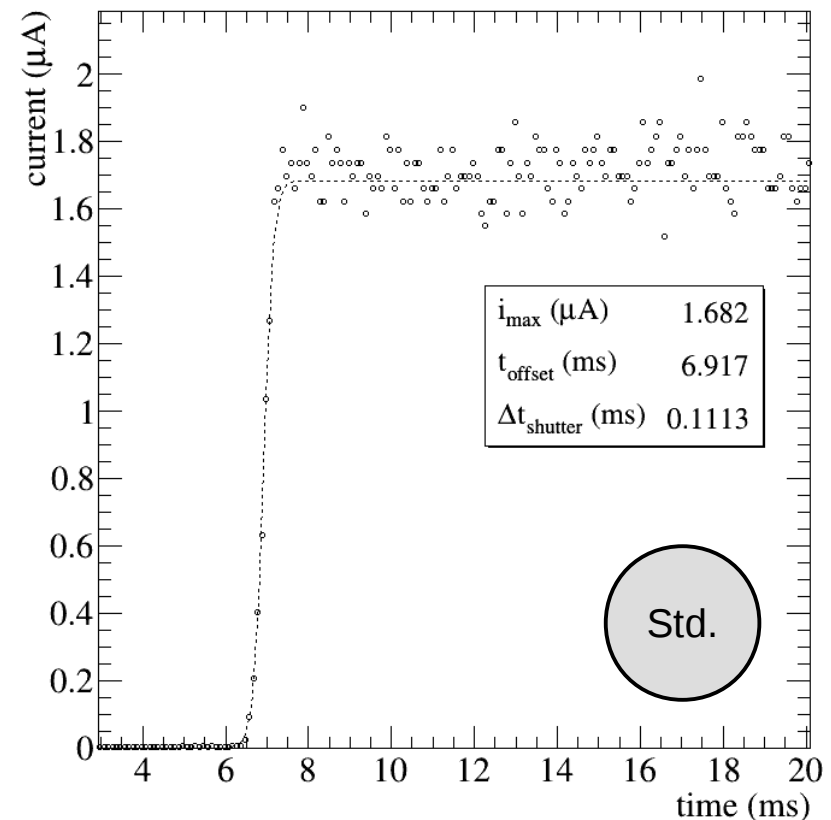
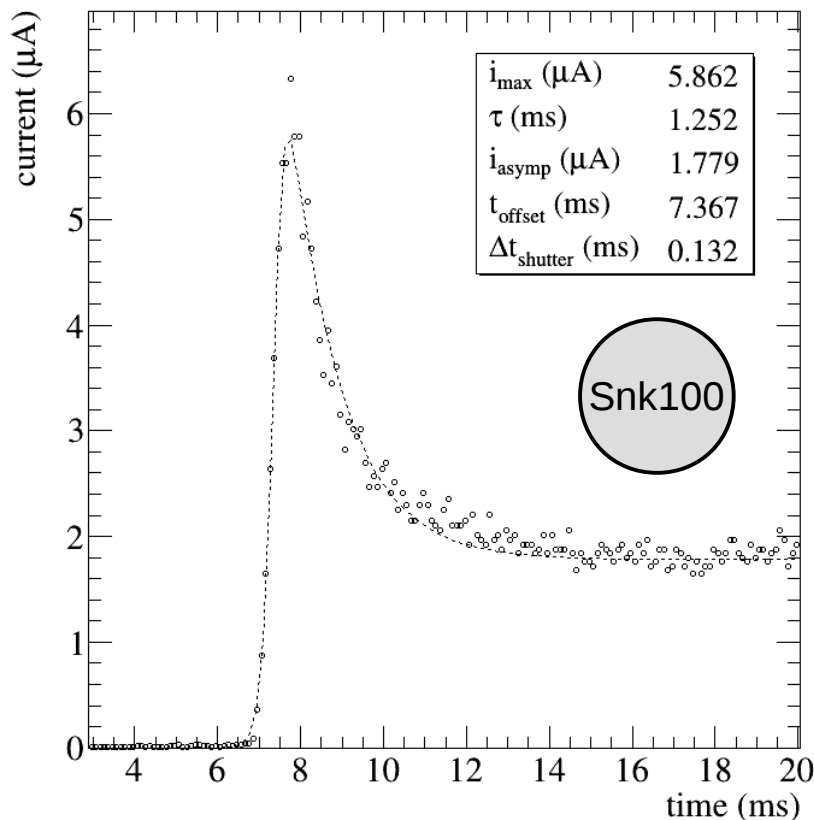
Measuring the relaxation time, once again

We see only the steady regime and miss the initial current peak

Try a faster readout : reading power supply → recording pad-current on scope
Sensitive current-meter ('FemtoBox') available in RD51 lab. at CERN

With the highest-R prototype, we measure a relaxation time of ~ 1.3 ms

We fit τ to the data (implicitly implies that the current decay is exponential)



Extrapolating the relaxation time

Reminder : 6 prototypes

2 different R-paste (100 VS 1 k Ω/\square)

3 different patterns (shape and number of via)

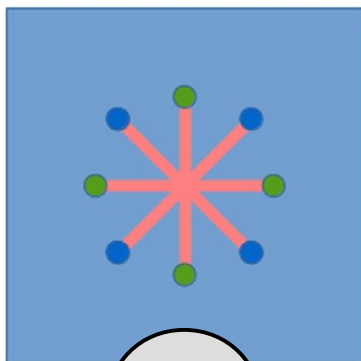
Likely : $\tau(\text{Snake1}) = 10^{-2} \cdot \tau(\text{Snake100}) \sim 10 \mu\text{s}$

Capacitance is the same for a given pattern

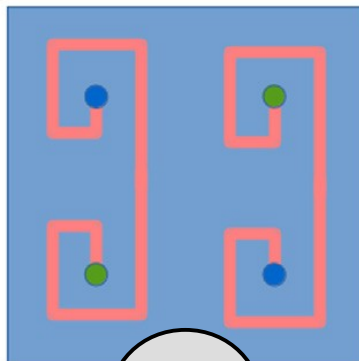
Likely : $\tau(\text{Snake}) > \tau(\text{Mirror}) > \tau(\text{Star})$

Indeed : R-embedded decreases (40-3-1) and N_{via} increases (1-2-4)

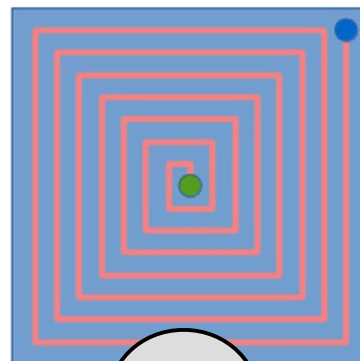
Lacking a diffusion model, difficult to be more quantitative



Star



Mirror



Snake

R-pad		
Insulator	Via	
R-embedded		
	Via	Insulator
RO-pad		

Measuring sparks

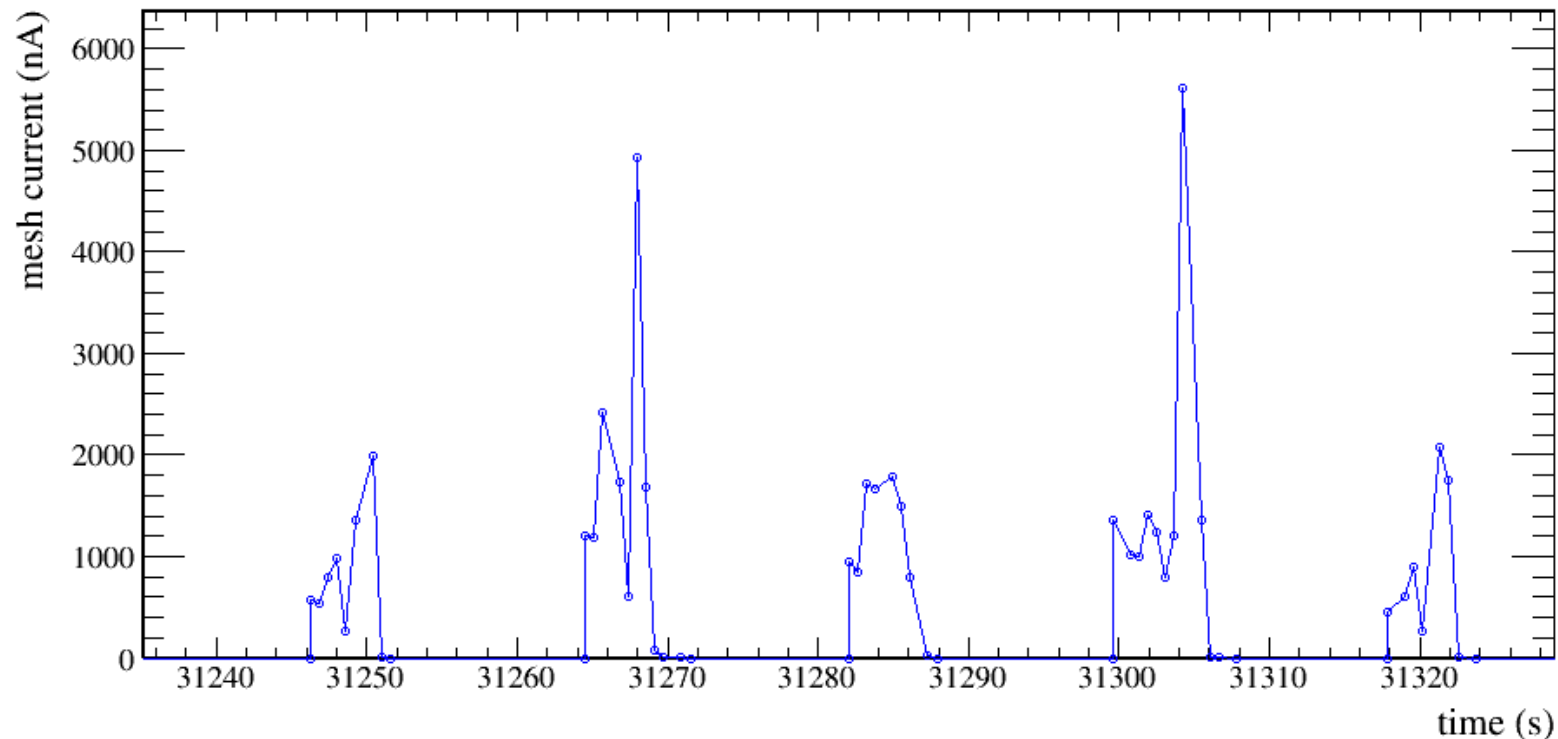
Create the 'conditions' :

High-energy (200 GeV) high-intensity (0.5-1-1.5 MHz) pion beam

Directed at a $2 \lambda_{\text{int}}$ thick steel absorber, prototype placed behind

Monitor mesh current, erratic behaviour signs occurrence of sparks

Compare trends from different prototypes



Std.

Measuring sparks

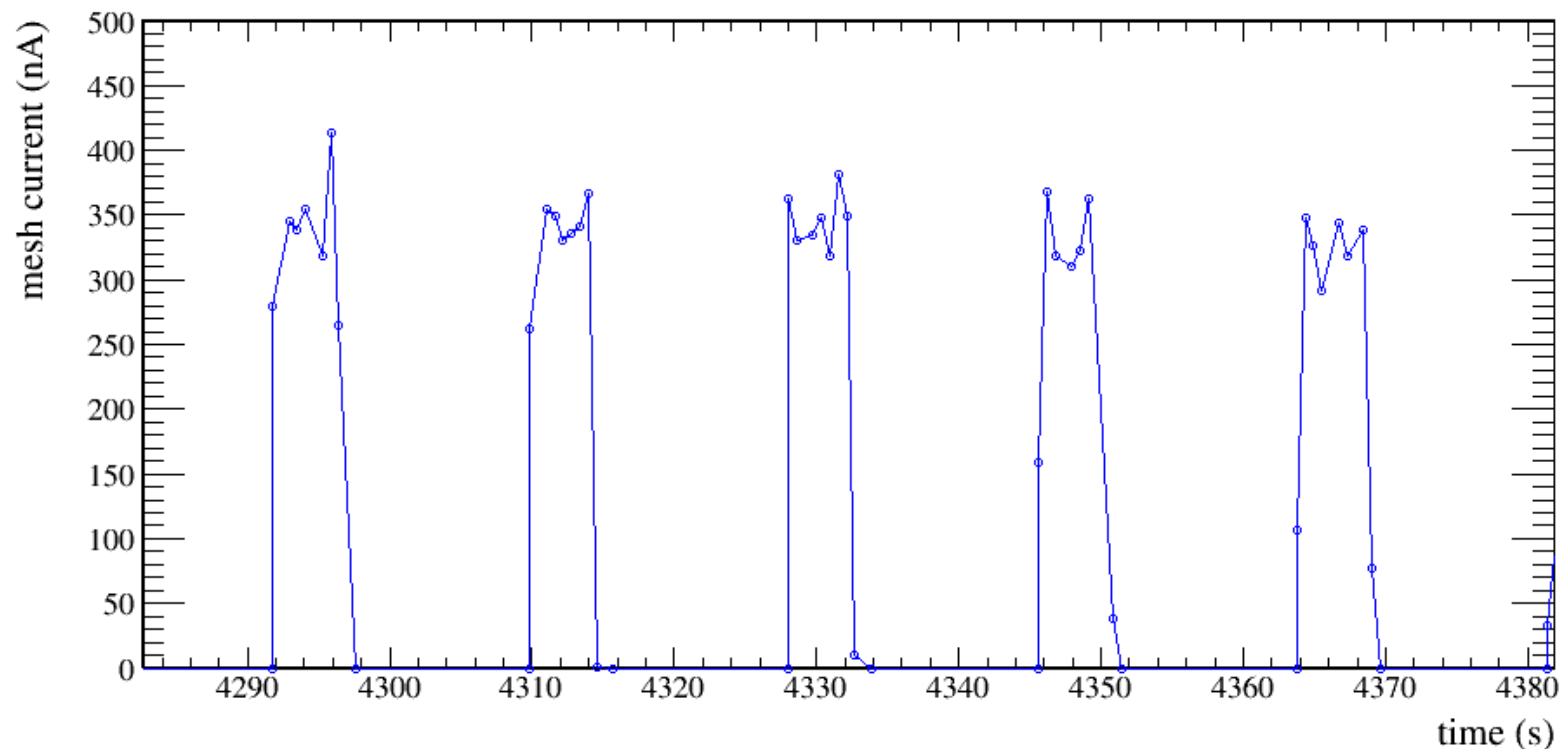
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Snk100

Measuring sparks

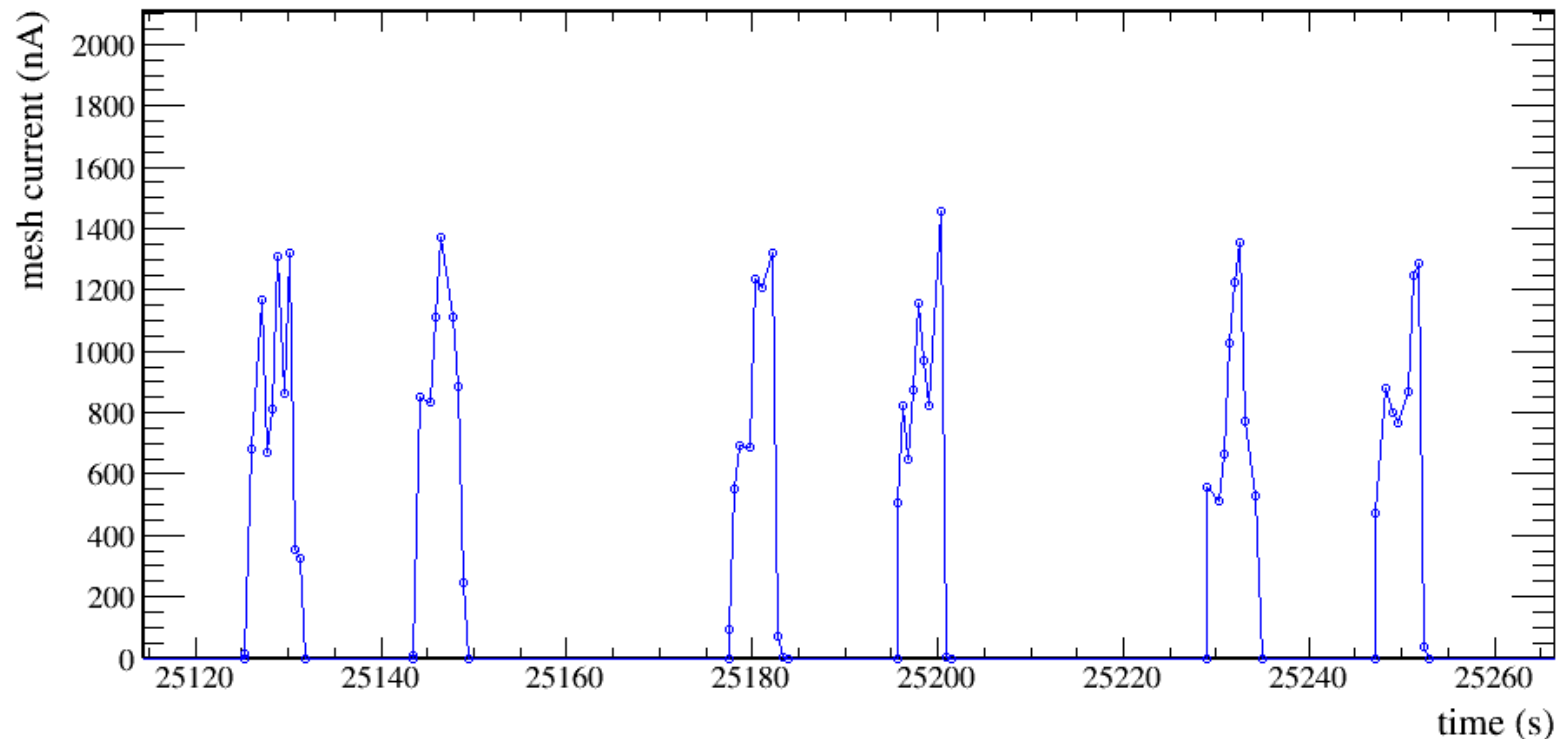
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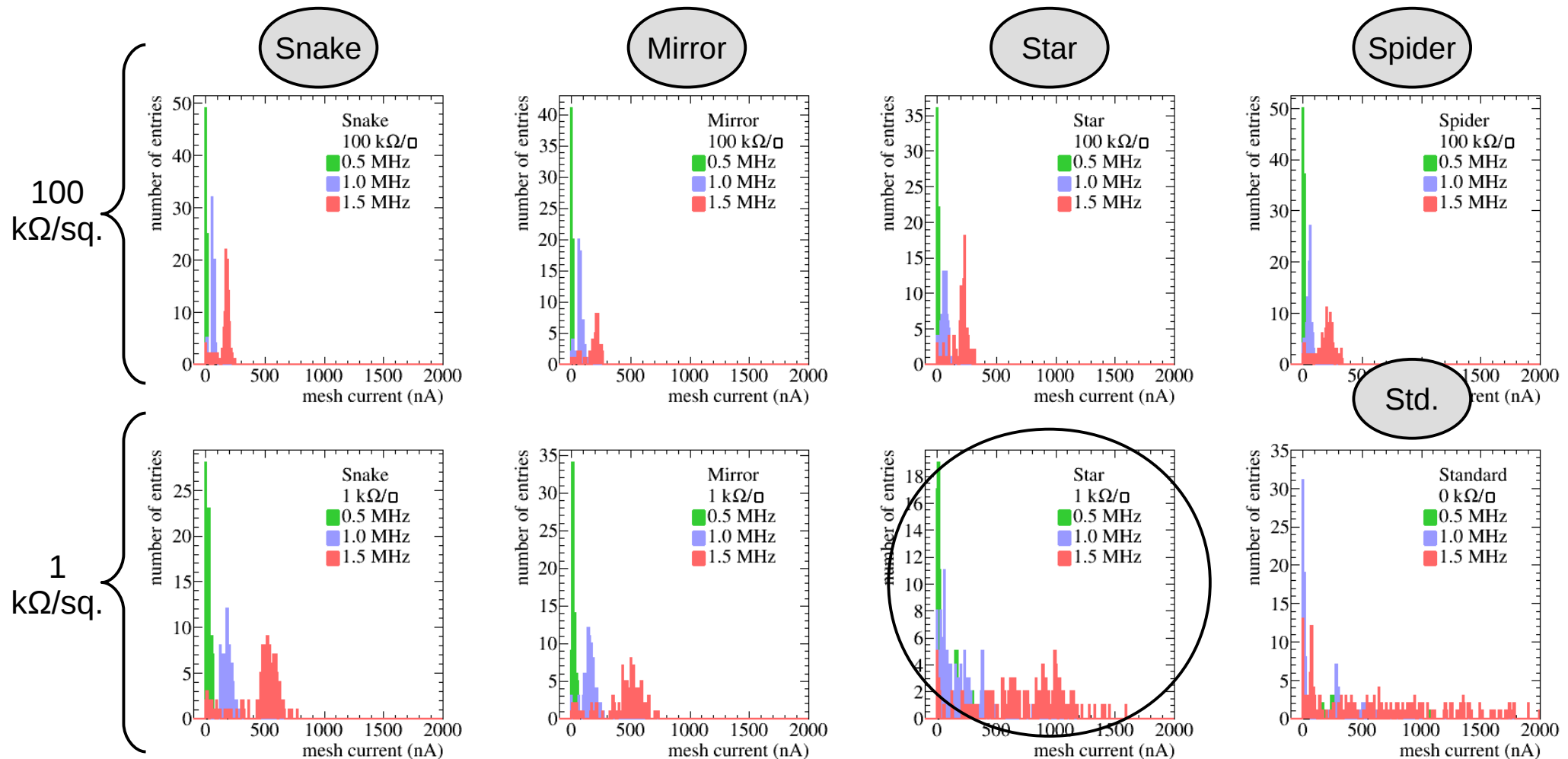


Star1

Measuring sparks

Compare trends from different prototypes : mesh-current distribution in spills

Indicate a Loss of spark quenching for the prototype of lowest R



Outro. 1

Naive extrapolation of τ based on R-ratio between Snake100 & Mirror1

Spark quenching is lost for τ shorter than $1 \text{ ms} / 100 / 10 = 1 \mu\text{s}$

Way larger than the time between successors of 1 ns but :

Extrapolated τ is probably over-estimated

Does not take into account the number of vias

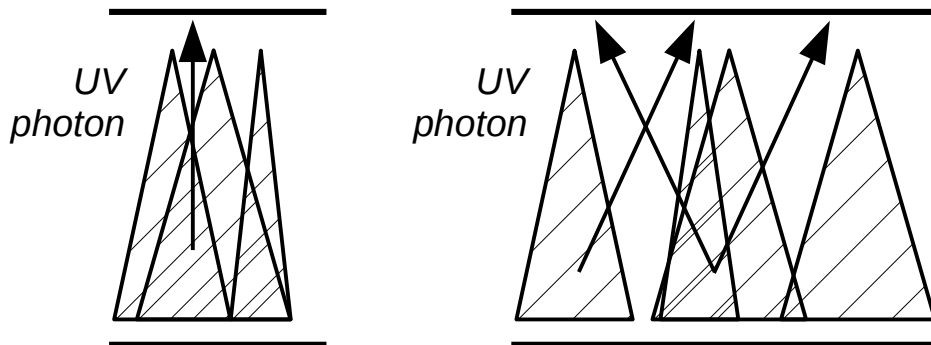
Model Δt is probably under-estimated

Toy MC does not account for lateral dispersion of successor avalanches

To conclude, we need

A better model of spark development (from 0-D to at least 2-D) $\rightarrow \Delta t$

A model of charge diffusion on R-pad $\rightarrow \tau$



Outro. 2

Spark-free operation at very-high rates (MHz/mm²) possible with embedded-R

Could be pushed even higher with 'closed' geometries, e.g. WELL-like
(as lateral photon feedback (or photo-ionisation) would be constrained)
Provided that each hole has its own embedded-R

Theoretical rate capability limit of such device could be Δt^{-1} / hole

That is : 1 GHz / hole (for a 128 μm ampli. gap) or beyond with smaller gaps

